MAX3227E
3-V TO 5.5-V SINGLE-CHANNEL RS-232 LINE DRIVER/RECEIVER WITH ±15-kV IEC ESD PROTECTION

SLLS715A – FEBRUARY 2006 – REVISED JUNE 2007

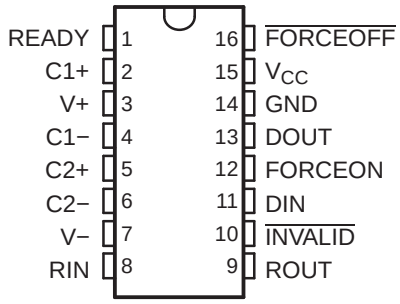
FEATURES

- **Meets or Exceeds the Requirements of TIA/EIA-232-F and ITU v.28 Standards**
- **Operates With 3-V to 5.5-V V_{CC} Supply**
- **Operates at Least 1 Mbit/s**
- **Low Standby Current . . . 1 µA Typ**
- **External Capacitors . . . 4 × 0.1 µF**
- **Accepts 5-V Logic Input With 3.3-V Supply**
- **Designed to Be Interchangeable With Maxim™ MAX3227E**
- **Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II**
- **ESD Protection for RS-232 I/O Pins**
  - **±15 kV – Human-Body Model**
  - **±8 kV – IEC61000-4-2, Contact Discharge**
  - **±15 kV – IEC61000-4-2, Air-Gap Discharge**
- **Auto-Powerdown Plus Feature Automatically Disables Drivers for Power Savings**
- **Packaged in Plastic Shrink Small-Outline Package**

APPLICATIONS

- **Battery-Powered, Hand-Held, and Portable Equipment**
- **PDAs and Palmtop PCs**
- **Notebooks, Sub-Notebooks, and Laptops**
- **Digital Cameras**
- **Mobile Phones and Wireless Devices**

DB PACKAGE
(TOP VIEW)



DESCRIPTION/ORDERING INFORMATION

The MAX3227E consists of one line driver, one line receiver, and a dual charge-pump circuit with ±15-kV IEC ESD protection pin to pin (serial-port connection pins, including GND). The device meets the requirements of TIA/EIA-232-F and provides the electrical interface between an asynchronous communication controller and the serial-port connector. The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. This device operates at data-signaling rates of 1 Mbit/s in normal operating mode and a maximum of 30-V/µs driver output slew rate. This device also features a logic-level output (READY) that asserts when the charge pump is regulating and the device is ready to begin transmitting.

The MAX3227E achieves a 1-µA supply current using the auto-powerdown plus feature. This device automatically enters a low-power powerdown mode when the RS-232 cable is disconnected or the drivers of the connected peripherals are inactive for more than 30 s. They turn on again when they sense a valid transition at any driver or receiver input. Auto-powerdown saves power without changes to the existing BIOS or operating system.

The MAX3227EC is characterized for operation from 0°C to 70°C. The MAX3227EI is characterized for operation from –40°C to 85°C.

ORDERING INFORMATION

T_A	PACKAGE(1)(2)		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	SSOP – DB	Tube of 80	MAX3227ECDB	MP227EC
		Reel of 2000	MAX3227ECDBR	
–40°C to 85°C	SSOP – DB	Tube of 80	MAX3227EIDB	MP227EI
		Reel of 2000	MAX3227EIDBR	

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.
(2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of the Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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FUNCTION TABLE(1)

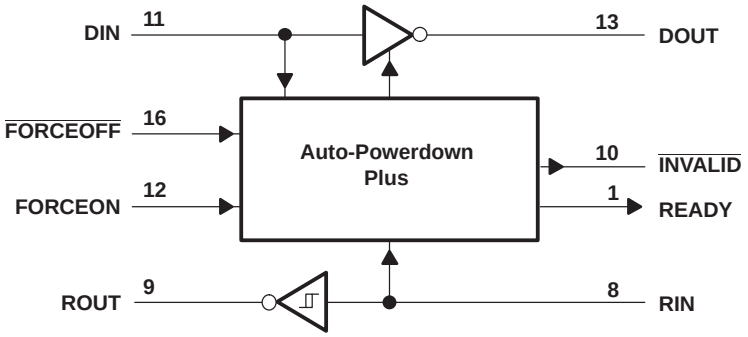
INPUT CONDITIONS				OUTPUT STATES				OPERATING MODE
FORCEON	$\overline{\text{FORCEOFF}}$	RECEIVER OR DRIVER EDGE WITHIN 30 s	VALID RS-232 LEVEL PRESENT AT RECEIVER	DRIVER	RECEIVER	$\overline{\text{INVALID}}$	READY	
Auto-Powerdown Plus Conditions								
H	H	NO	NO	Active	Active	L	H	Normal operation, auto-powerdown plus disabled
H	H	NO	YES	Active	Active	H	H	Normal operation, auto-powerdown plus disabled
L	H	YES	NO	Active	Active	L	H	Normal operation, auto-powerdown plus enabled
L	H	YES	YES	Active	Active	H	H	Normal operation, auto-powerdown plus enabled
L	H	NO	NO	Z	Active	L	L	Powerdown, auto-powerdown plus enabled
L	H	NO	YES	Z	Active	H	L	Powerdown, auto-powerdown plus enabled
X	L	X	NO	Z	Active	L	L	Manual powerdown
X	L	X	YES	Z	Active	H	L	Manual powerdown
Auto-Powerdown Conditions								
$\overline{\text{INVALID}}$	$\overline{\text{INVALID}}$	X	NO	Z	Active	L	L	Powerdown, auto-powerdown enabled
$\overline{\text{INVALID}}$	$\overline{\text{INVALID}}$	X	YES	Active	Active	H	H	Normal operation, auto-powerdown enabled

(1) H = high level, L = low level, X = irrelevant, Z = high impedance

TERMINAL FUNCTIONS

TERMINAL		DESCRIPTION
NAME	NO.	
C1+	2	Positive terminal of voltage-doubler charge-pump capacitor
C1–	4	Negative terminal of voltage-doubler charge-pump capacitor
C2+	5	Positive terminal of inverting charge-pump capacitor
C2–	6	Negative terminal of inverting charge-pump capacitor
DIN	11	CMOS driver input
DOUT	13	RS-232 driver output
$\overline{\text{FORCEOFF}}$	16	Force-off input, active low. Drive low to shut down drivers, receivers, and charge pump. This overrides auto-shutdown and FORCEON (see Function Table).
FORCEON	12	Force-on input, active high. Drive high to override powerdown, keeping drivers and receivers on ($\overline{\text{FORCEOFF}}$ must be high) (see Function Table).
GND	14	Ground
$\overline{\text{INVALID}}$	10	Valid signal detector output, active low. A logic high indicates that a valid RS-232 level is present on a receiver input.
READY	1	Ready to transmit output, active high. READY is enabled high when V– goes below –3.5 V and the device is ready to transmit.
RIN	8	RS-232 receiver input
ROUT	9	CMOS receiver output
V+	3	$+2 \times V_{CC}$ generated by the charge pump
V–	7	$-2 \times V_{CC}$ generated by the charge pump
V_{CC}	15	3-V to 5.5-V single-supply voltage

LOGIC DIAGRAM (POSITIVE LOGIC)



Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range(2)		–0.3	6	V
V+	Positive output supply voltage range(2)		–0.3	7	V
V–	Negative output supply voltage range(2)		0.3	–7	V
V+ – V–	Supply voltage difference(2)			13	V
V_I	Input voltage range	Driver ($\overline{\text{FORCEOFF}}$, FORCEON)	–0.3	6	V
		Receiver	–25	25	
V_O	Output voltage range	Driver	–13.2	13.2	V
		Receiver ($\overline{\text{INVALID}}$, READY)	–0.3	V_{CC} + 0.3	
	Short-circuit duration	DOUT to GND		Unlimited	
θ_{JA}	Package thermal impedance(3)			82	°C/W
	Lead temperature 1,6 mm (1/16 in) from case for 10 s			260	°C
T_{stg}	Storage temperature range		–65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltages are with respect to network GND.
(3) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions(1)

See Figure 5

				MIN	NOM	MAX	UNIT
	Supply voltage		V_{CC} = 3.3 V	3	3.3	3.6	V
			V_{CC} = 5 V	4.5	5	5.5	
V_{IH}	Driver and control high-level input voltage	DIN, $\overline{\text{FORCEOFF}}$, FORCEON	V_{CC} = 3.3 V	2		5.5	V
			V_{CC} = 5 V	2.4		5.5	
V_{IL}	Driver and control low-level input voltage	DIN, $\overline{\text{FORCEOFF}}$, FORCEON		0		0.8	V
V_I	Receiver input voltage			–25		25	V
T_A	Operating free-air temperature		MAX3227EC	0		70	°C
			MAX3227EI	–40		85	

(1) Test conditions are C1–C4 = 0.1 µF at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 µF, C2–C4 = 0.33 µF at V_{CC} = 5 V ± 0.5 V.

Electrical Characteristics(1)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

PARAMETER			TEST CONDITIONS	MIN	TYP(2)	MAX	UNIT
I_I	Input leakage current	$\overline{\text{FORCEOFF}}$, FORCEON			±0.01	±1	µA
I_{CC}	Supply current (T_A = 25°C)	Auto-powerdown plus disabled	No load, $\overline{\text{FORCEOFF}}$ and FORCEON at V_{CC}		0.3	2	mA
		Powered off	No load, $\overline{\text{FORCEOFF}}$ at GND		1	10	µA
		Auto-powerdown plus enabled	No load, $\overline{\text{FORCEOFF}}$ at V_{CC}, FORCEON at GND, All RIN are open or grounded		1	10	

(1) Test conditions are C1–C4 = 0.1 µF at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 µF, C2–C4 = 0.33 µF at V_{CC} = 5 V ± 0.5 V.
(2) All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

DRIVER SECTION

Electrical Characteristics(1)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)
(see Figure 1 and Figure 2)

PARAMETER		TEST CONDITIONS			MIN	TYP(2)	MAX	UNIT
V_{OH}	High-level output voltage	DOUT at R_L = 3 kΩ to GND,	DIN = GND		5	5.4		V
V_{OL}	Low-level output voltage	DOUT at R_L = 3 kΩ to GND,	DIN = V_{CC}		–5	–5.4		V
I_{IH}	High-level input current	V_I = V_{CC}				±0.01	±1	µA
I_{IL}	Low-level input current	V_I at GND				±0.01	±1	µA
I_{OS}	Short-circuit output current(3)	V_{CC} = 3.6 V,	V_O = 0 V			±35	±60	mA
		V_{CC} = 5.5 V,	V_O = 0 V			±35	±60	
r_o	Output resistance	V_{CC}, V+, and V– = 0 V,	V_O = ±2 V		300	10M		Ω
I_{off}	Output leakage current	$\overline{FORCEOFF}$ = GND,	V_O = ±12 V,	V_{CC} = 0 to 5.5 V			±25	µA

(1) Test conditions are C1–C4 = 0.1 µF at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 µF, C2–C4 = 0.33 µF at V_{CC} = 5 V ± 0.5 V.
(2) All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.
(3) Short-circuit durations should be controlled to prevent exceeding the device absolute power dissipation ratings, and not more than one output should be shorted at a time.

Switching Characteristics(1)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)
(see Figure 1 and Figure 2)

PARAMETER		TEST CONDITIONS			MIN	TYP(2)	MAX	UNIT
Maximum data rate		C_L = 1000 pF, One DIN switching,	R_L = 3 kΩ, See Figure 1		250			kbit/s
		C_L = 1000 pF, V_{CC} = 4.5 V,	R_L = 3 kΩ, See Figure 1	One DIN switching,	1000			
		C_L = 250 pF, V_{CC} = 3 V,	R_L = 3 kΩ, See Figure 1	One DIN switching,	1000			
$t_{sk(p)}$	Pulse skew(3)	C_L = 150 pF to 2500 pF,	R_L = 3 kΩ to 7 kΩ,	See Figure 2		25		ns
SR(tr)	Slew rate, transition region	V_{CC} = 3.3 V, C_L = 150 pF to 1000 pF,	R_L = 3 kΩ to 7 kΩ, See Figure 1		24		150	V/µs

(1) Test conditions are C1–C4 = 0.1 µF at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 µF, C2–C4 = 0.33 µF at V_{CC} = 5 V ± 0.5 V.
(2) All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.
(3) Pulse skew is defined as $|t_{PLH} - t_{PHL}|$ of each channel of the same device.

ESD Protection

TERMINAL		TEST CONDITIONS	TYP	UNIT
NAME	NO.			
DOUT	13	Human-Body Model	±15	kV
		Contact Discharge (IEC61000-4-2)	±8	
		Air-Gap Discharge (IEC61000-4-2)	±15	

RECEIVER SECTION

Electrical Characteristics(1)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 3)

PARAMETER		TEST CONDITIONS	MIN	TYP(2)	MAX	UNIT
V_{OH}	High-level output voltage	I_{OH} = –1 mA	V_{CC} – 0.6	V_{CC} – 0.1		V
V_{OL}	Low-level output voltage	I_{OL} = 1.6 mA			0.4	V
V_{IT+}	Positive-going input threshold voltage	V_{CC} = 3.3 V		1.5	2.4	V
		V_{CC} = 5 V		1.8	2.4	
$V_{IT–}$	Negative-going input threshold voltage	V_{CC} = 3.3 V	0.6	1.2		V
		V_{CC} = 5 V	0.8	1.5		
V_{hys}	Input hysteresis (V_{IT+} – $V_{IT–}$)			0.5		V
I_{off}	Output leakage current			±0.05	±10	µA
r_i	Input resistance	V_I = ±3 V to ±25 V	3	5	7	kΩ

(1) Test conditions are C1–C4 = 0.1 µF at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 µF, C2–C4 = 0.33 µF at V_{CC} = 5 V ± 0.5 V.
(2) All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

Switching Characteristics(1)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	TYP(2)	UNIT
t_{PLH}	Propagation delay time, low- to high-level output	C_L = 150 pF, See Figure 3	150	ns
t_{PHL}	Propagation delay time, high- to low-level output	C_L = 150 pF, See Figure 3	150	ns
$t_{sk(p)}$	Pulse skew(3)	See Figure 3	50	ns

(1) Test conditions are C1–C4 = 0.1 µF at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 µF, C2–C4 = 0.33 µF at V_{CC} = 5 V ± 0.5 V.
(2) All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.
(3) Pulse skew is defined as $|t_{PLH} - t_{PHL}|$ of each channel of the same device.

ESD Protection

TERMINAL		TEST CONDITIONS	TYP	UNIT
NAME	NO.			
RIN	8	Human-Body Model	±15	kV
		Contact Discharge (IEC61000-4-2)	±8	
		Air-Gap Discharge (IEC61000-4-2)	±15	

AUTO-POWERDOWN SECTION

Electrical Characteristics

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 4)

PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
$V_{T+(valid)}$	Receiver input threshold for $\overline{INVALID}$ high-level output voltage	FORCEON = GND, $\overline{FORCEOFF}$ = V_{CC}		2.7	V
$V_{T-(valid)}$	Receiver input threshold for $\overline{INVALID}$ high-level output voltage	FORCEON = GND, $\overline{FORCEOFF}$ = V_{CC}	–2.7		V
$V_{T(invalid)}$	Receiver input threshold for $\overline{INVALID}$ low-level output voltage	FORCEON = GND, $\overline{FORCEOFF}$ = V_{CC}	–0.3	0.3	V
V_{OH}	$\overline{INVALID}$, READY output voltage high	I_{OH} = –1 mA, FORCEON = GND, $\overline{FORCEOFF}$ = V_{CC}	V_{CC} – 0.6		V
V_{OL}	$\overline{INVALID}$, READY output voltage low	I_{OL} = 1.6 mA, FORCEON = GND, $\overline{FORCEOFF}$ = V_{CC}		0.4	V

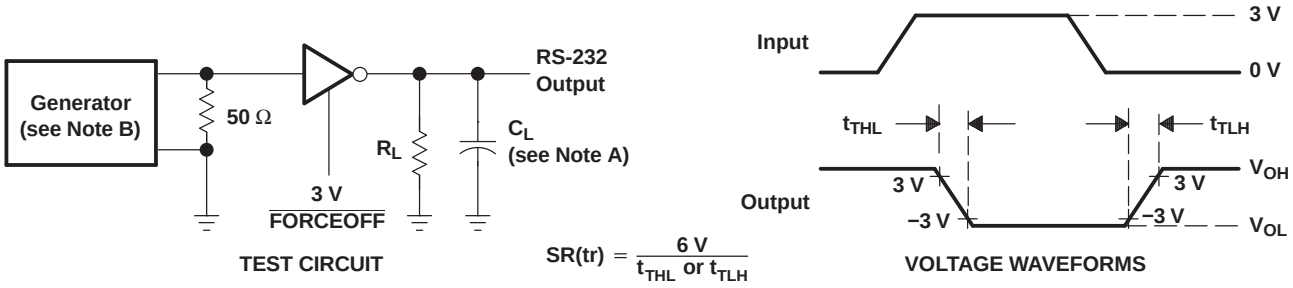
Switching Characteristics

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 4)

PARAMETER			MIN	TYP(1)	MAX	UNIT
t_{INVH}	Propagation delay time, low- to high-level output			1		µs
t_{INVL}	Propagation delay time, high- to low-level output			30		µs
t_{WU}	Supply enable time			100		µs
$t_{AUTOPRDN}$	Driver or receiver edge to driver's shutdown	V_{CC} = 5 V	15	30	60	s

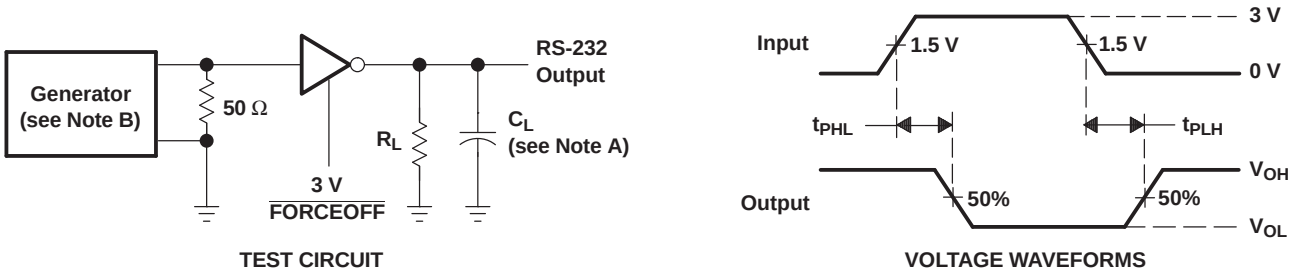
(1) All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

PARAMETER MEASUREMENT INFORMATION



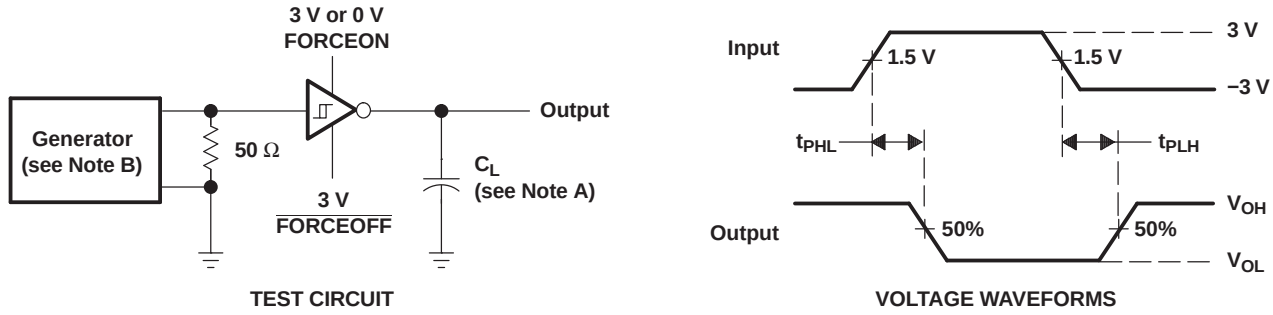
NOTES: A. C_L includes probe and jig capacitance.
B. The pulse generator has the following characteristics: PRR = 250 kbit/s, Z_O = 50 Ω, 50% duty cycle, $t_r \le 10$ ns, $t_f \le 10$ ns.

Figure 1. Driver Slew Rate



NOTES: A. C_L includes probe and jig capacitance.
B. The pulse generator has the following characteristics: PRR = 250 kbit/s, Z_O = 50 Ω, 50% duty cycle, $t_r \le 10$ ns, $t_f \le 10$ ns.

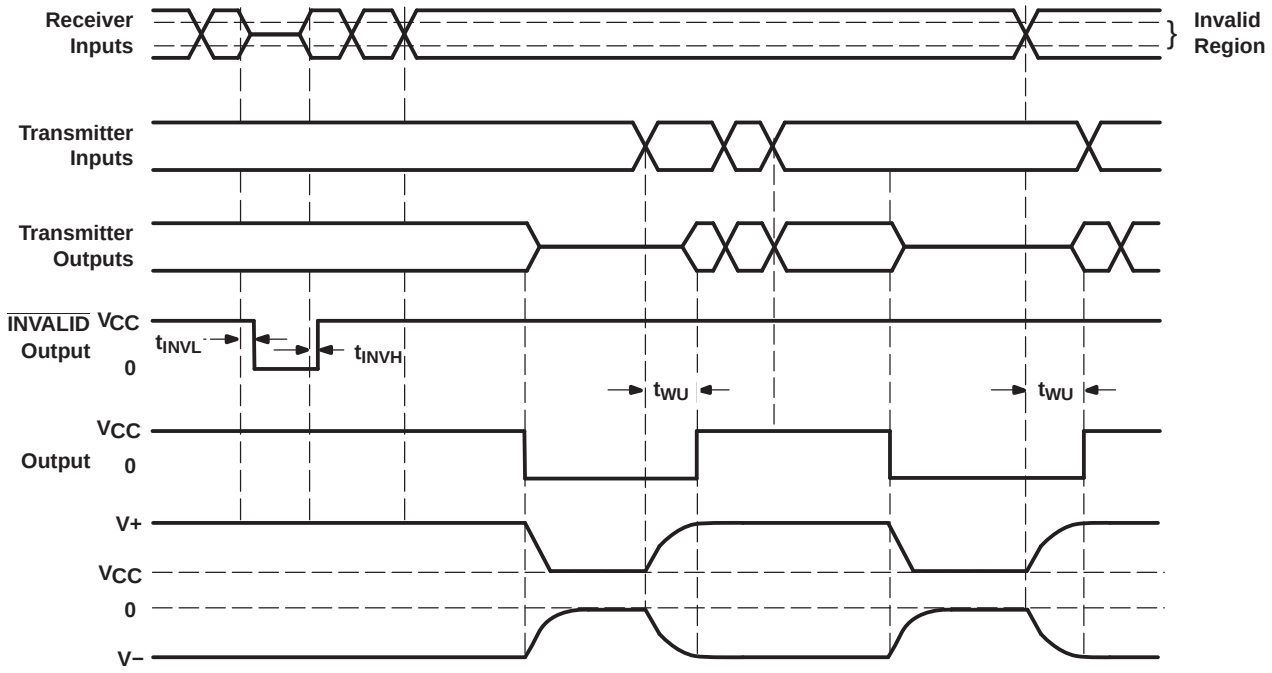
Figure 2. Driver Pulse Skew



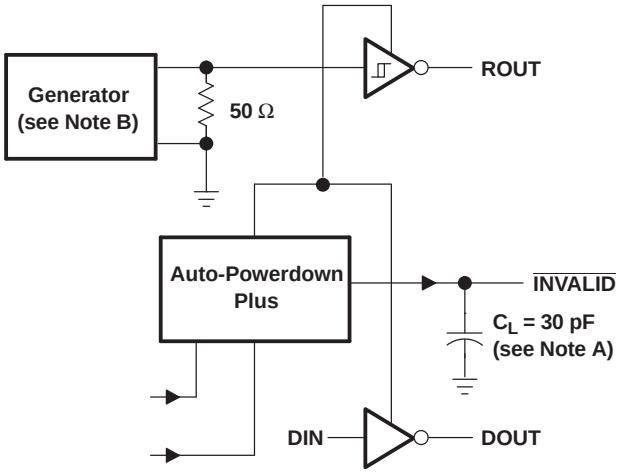
NOTES: A. C_L includes probe and jig capacitance.
B. The pulse generator has the following characteristics: Z_O = 50 Ω, 50% duty cycle, $t_r \le 10$ ns, $t_f \le 10$ ns.

Figure 3. Receiver Propagation Delay Times

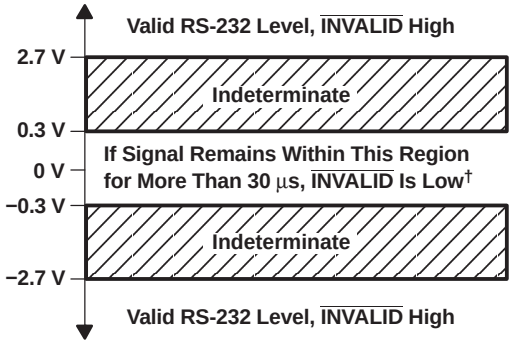
PARAMETER MEASUREMENT INFORMATION (continued)



VOLTAGE WAVEFORMS



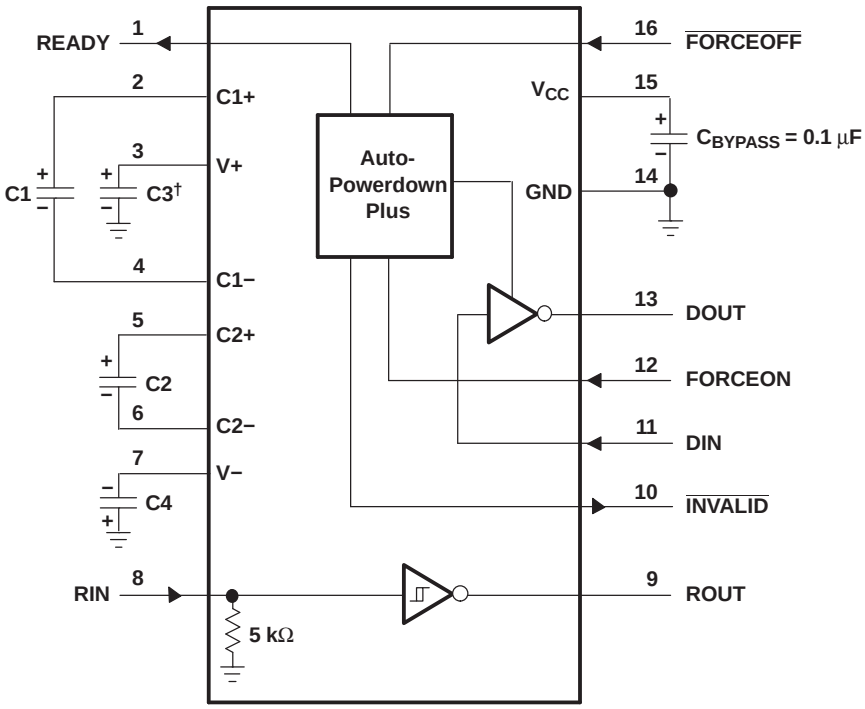
TEST CIRCUIT



† Auto-powerdown disables drivers and reduces supply current to 1 µA.

Figure 4. $\overline{\text{INVALID}}$ Propagation Delay Times and Driver Enabling Time

APPLICATION INFORMATION



† C3 can be connected to V_{CC} or GND.

NOTES: A. Resistor values shown are nominal.

B. Nonpolarized ceramic capacitors are acceptable. If polarized tantalum or electrolytic capacitors are used, they should be connected as shown.

V_{CC} vs CAPACITOR VALUES

V_{CC}	C1	C2, C3, and C4
3.3 V ± 0.3 V	0.1 µF	0.1 µF
5 V ± 0.5 V	0.047 µF	0.33 µF
3 V to 5.5 V	0.1 µF	0.47 µF

Figure 5. Typical Operating Circuit and Capacitor Values

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
MAX3227ECDB	ACTIVE	SSOP	DB	16	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3227ECDBG4	ACTIVE	SSOP	DB	16	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3227ECDBR	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3227ECDBRG4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3227EIDB	ACTIVE	SSOP	DB	16	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3227EIDBG4	ACTIVE	SSOP	DB	16	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3227EIDBR	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3227EIDBRG4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

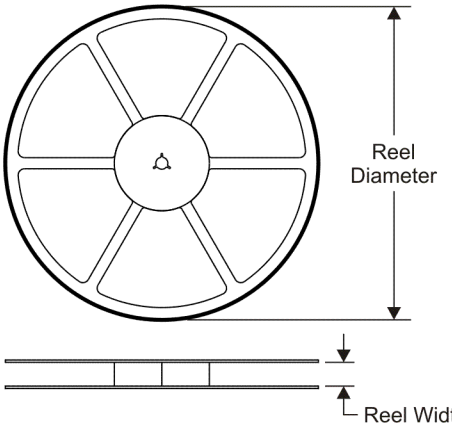
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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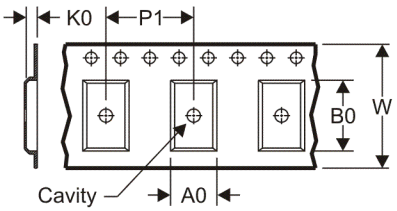
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TAPE AND REEL INFORMATION

REEL DIMENSIONS

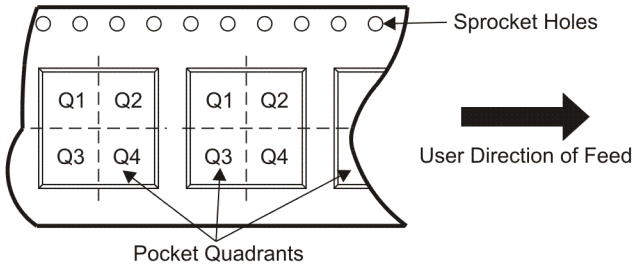


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

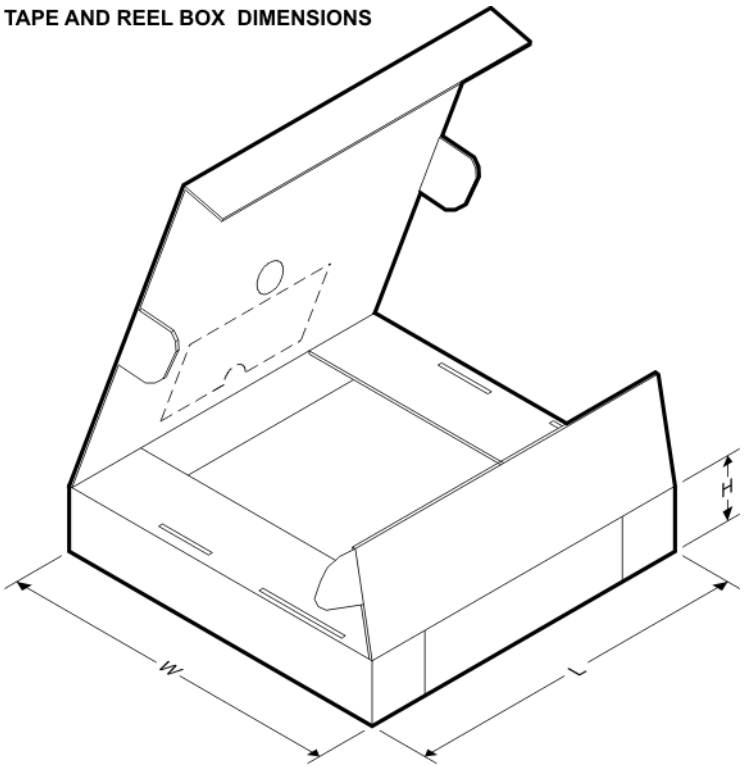
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
MAX3227ECDBR	SSOP	DB	16	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
MAX3227EIDBR	SSOP	DB	16	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



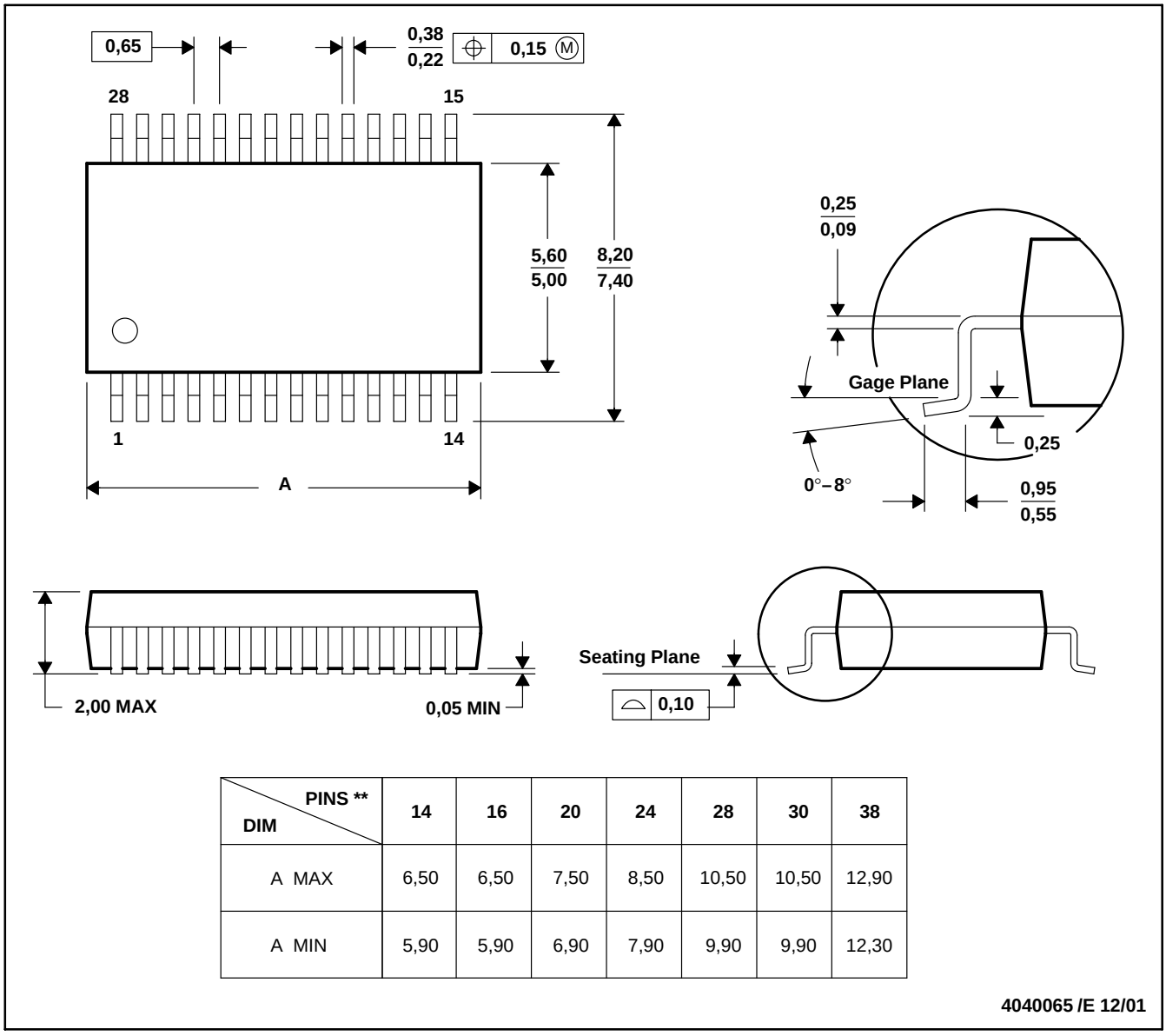
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
MAX3227ECDBR	SSOP	DB	16	2000	346.0	346.0	33.0
MAX3227EIDBR	SSOP	DB	16	2000	346.0	346.0	33.0

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DB (R-PDSO-G)** **PLASTIC SMALL-OUTLINE**

28 PINS SHOWN



DIM \ PINS **	14	16	20	24	28	30	38
A MAX	6,50	6,50	7,50	8,50	10,50	10,50	12,90
A MIN	5,90	5,90	6,90	7,90	9,90	9,90	12,30

4040065 /E 12/01

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-150

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